SPECIFICATION

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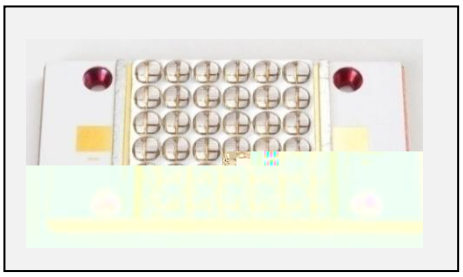
. lig P-45(e(ca)41uo)]TJETBT1 0 0 1 383.14 317.37 Tm[t(o)-3(n63(s)]TJET EMC /Span /MCID 024>BDC BT/F6

1. Description

1.1 General Description



This production use the Copper substrate and glass package outline size25X50X5.2mm

1.2 Features

► Copper substrate and glass package.

► Viewing angle:60°.

► RoHS compliant.

► Package:1pcs/bag.

1.3 Application

► UV Curing.

► UV Ink Curing.

► UV printing.

► Ultraviolet disinfection.

► General use.

1.5 Product Parameters

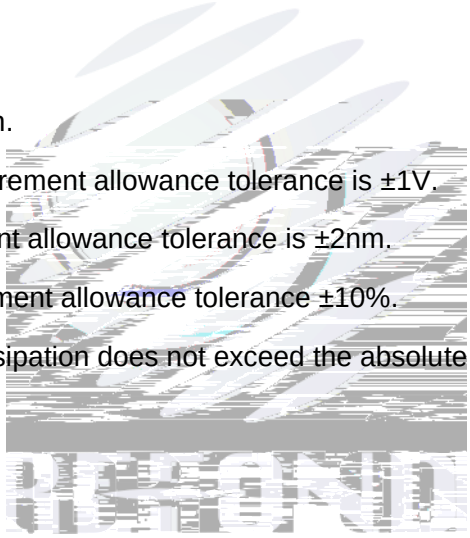
Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Code	Value			Unit
				Min.	Typ	Max.	
Forward Voltage	V_F	I_F=6.6A	C02	30	---	40	V
			C03	40	---	50	
Enitting Area Size	S	---	---	25*25			mm
Chip connection Arrangement	----	----	----	12S12P			---
Total radiant flux ! RT25E9-COBUBP-1212 (365-370nm)	Φ_e	I_F=6.6A	1A13	12	---	14.5	W/cm^2
			1A14	14.5	15	17.5	
			1A15	17.5	---	21	
Total radiant flux ! RT25E9-COBUEP-1212 (380-390nm)	Φ_e						

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Notes

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is ±1V.
3. The above wavelenth measurement allowance tolerance is ±2nm. ±
4. The above radiation flux measurement allowance tolerance ±10%.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.



1.6 Typical optical characteristics curves

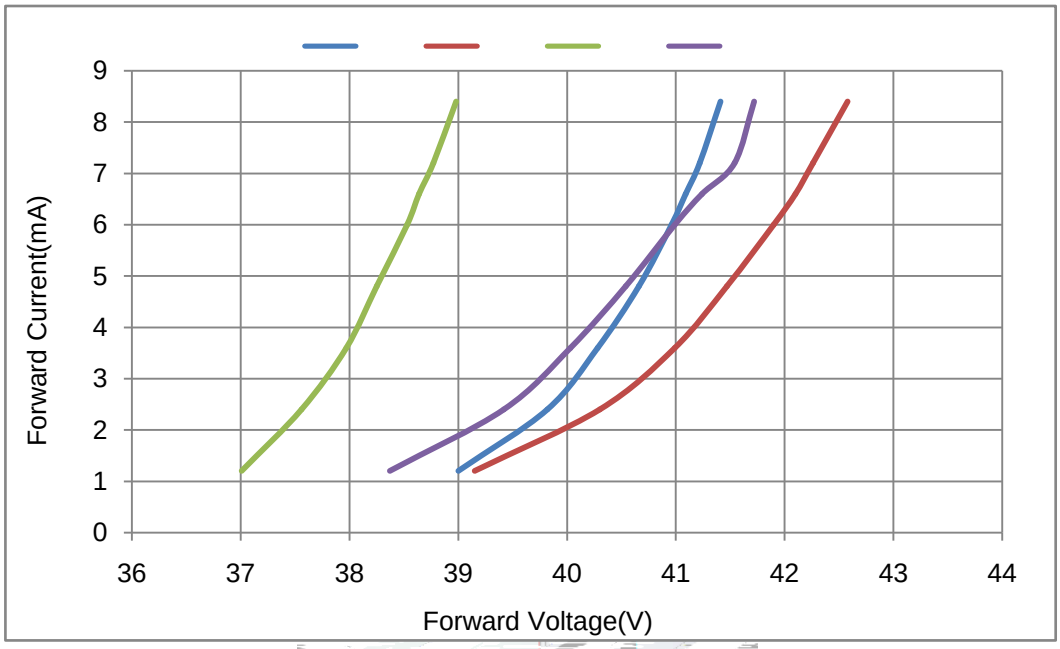


Fig.1- Forward Voltage Vs. Forward Current

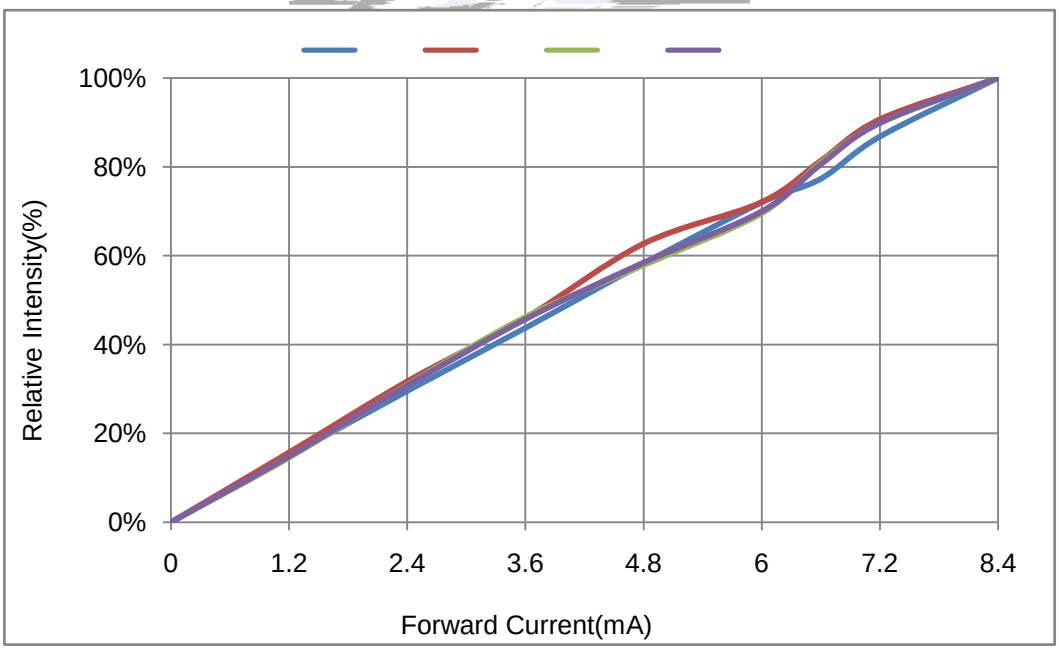


Fig.2- Forward Current Vs. Relative Power

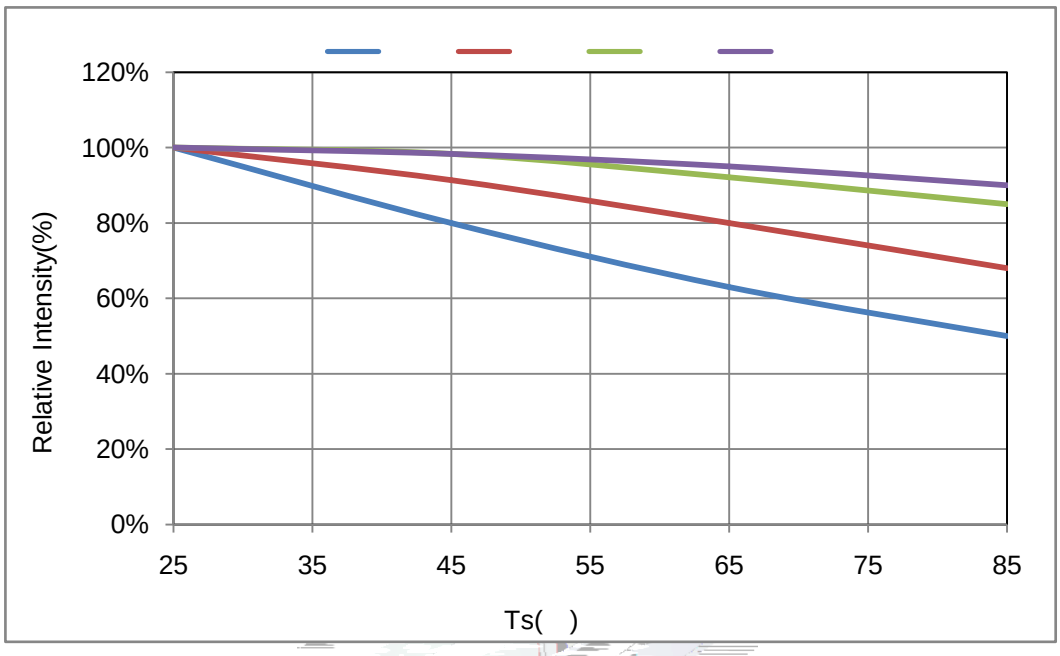


Fig.3-Solder Temperature VS. Relative Power

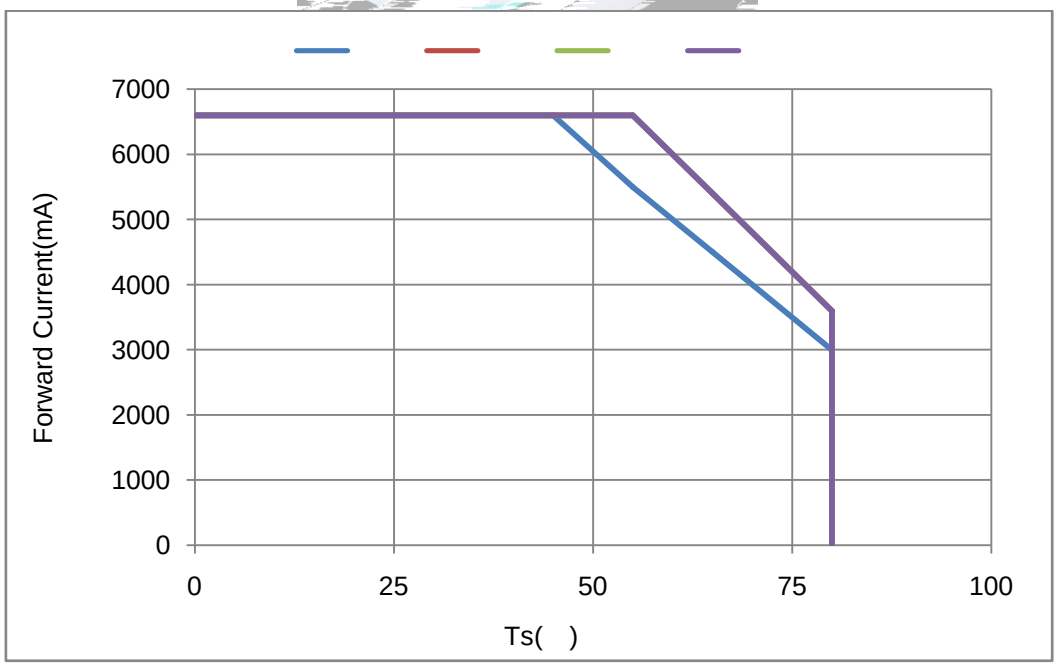


Fig.4-Ts Temperature VS. Forward Current

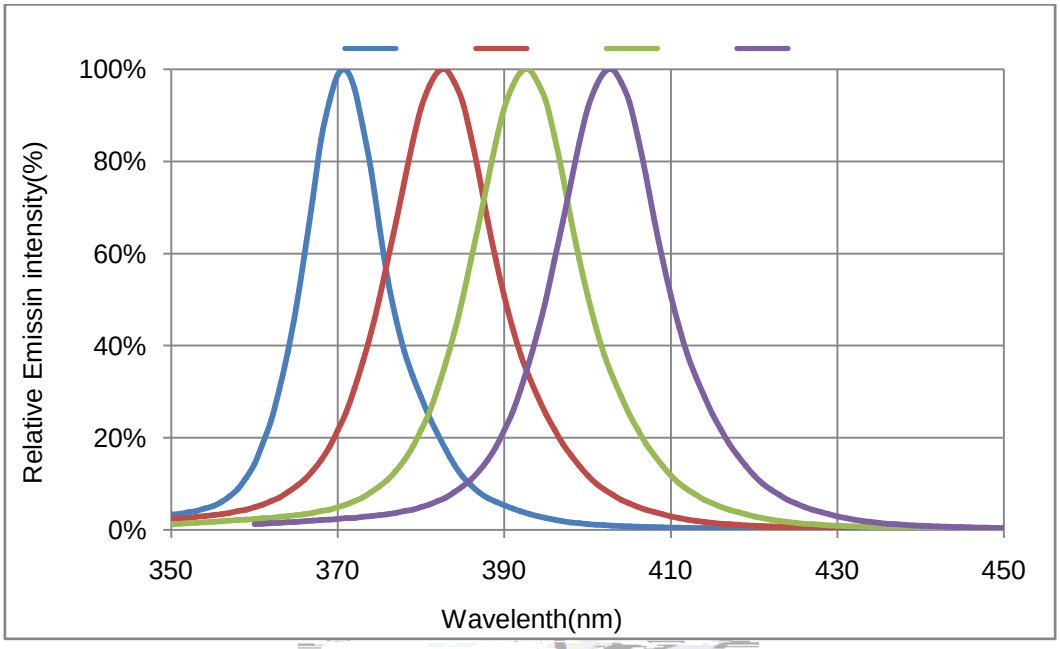
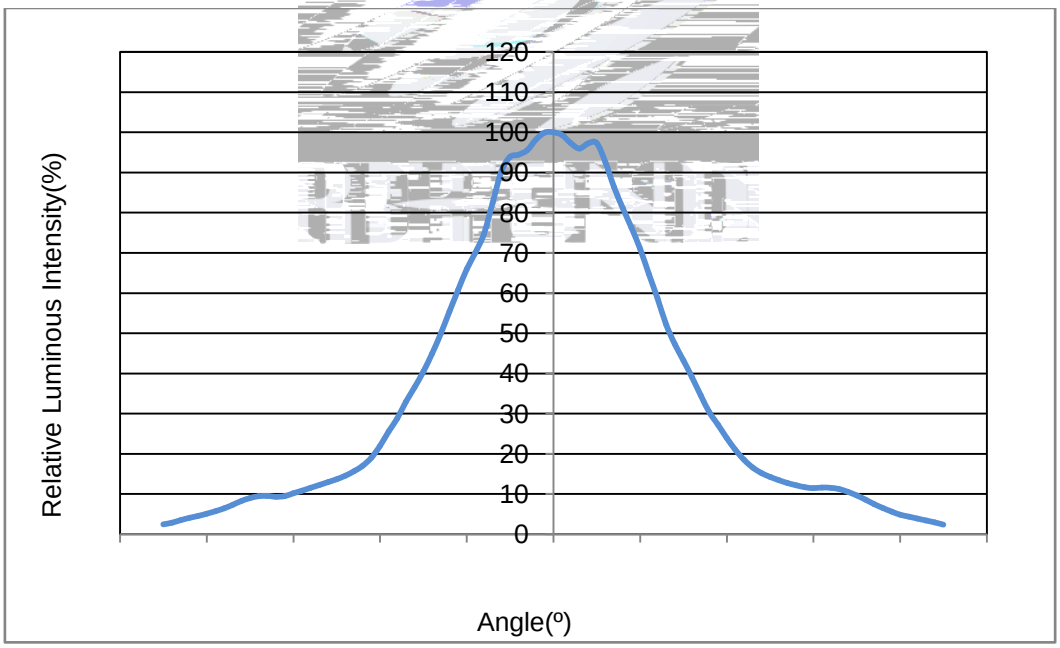


Fig.5-Spectrum Distribution



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2. Packaging

2.1 Packaging Specification

Package: 1pcs/bag.

2.1.1 Label Form Specification

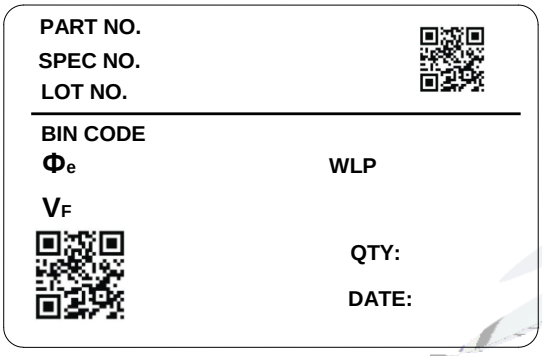


Fig. 2-1 Label Form Specification

Label Form Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ_e	Radiation flux
V_F	Forward Voltage
WLP	Wavelength
QTY	Packing Quantity
DATE	Made Date

2.2 Cardboard Box

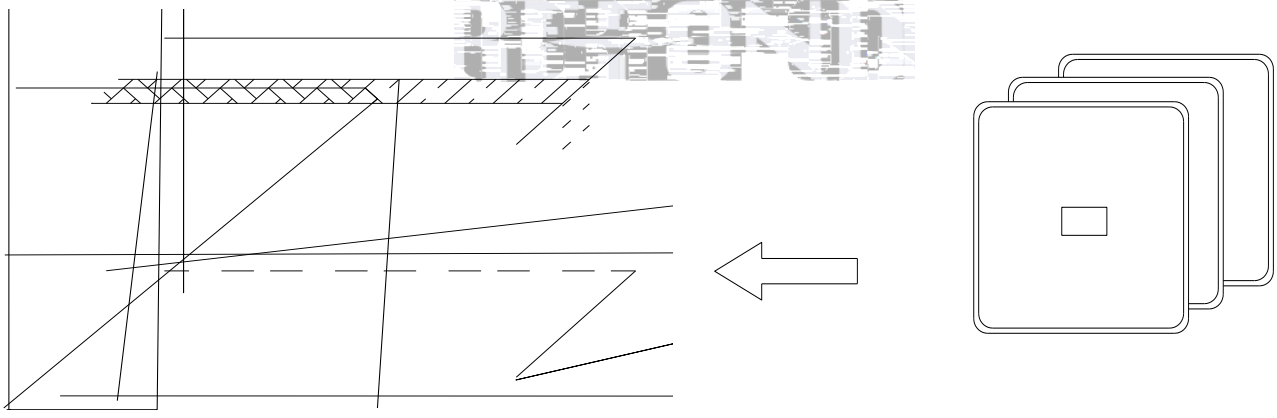


Fig.2-2 Cardboard Box

Tel: +86-755-66839118 Fax:+86-755-66839300 E-mail:uvsales@refond.com W

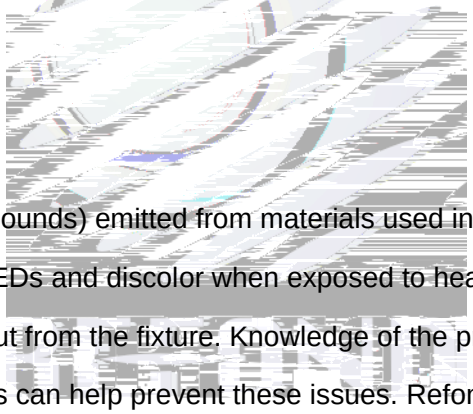
3. Handling Precautions

3.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LEDmating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

LED

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.



(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against theuse of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verifycompatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended tobe used. Attaching LEDs, do not use adhesives that outgas organic vapor.

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directlytouch or Handle the silicone lens surface, it may damage the internal circuitry.

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile,resistors for protection should be applied, otherwise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.

LED

The high temperature will make the LED's Luminous Intensity deceased radically, if LEDs worked in hot environment for a long time, they will be disabled easily. When LEDs are working in a closed array, we suggest that the LED's surface temperature should be lower than 45 and the leg's temperature should be lower than 65 .

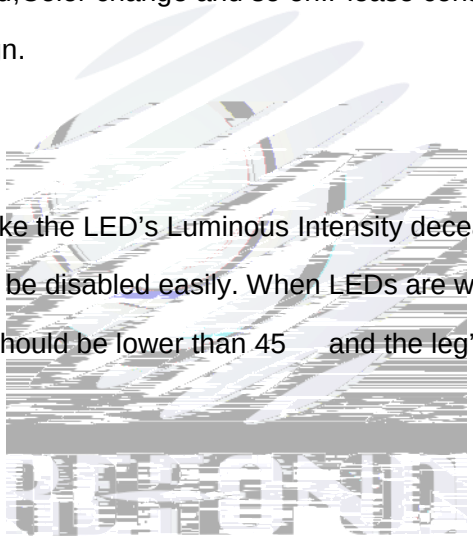


Table 3-1Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60 5	-	24hours 24

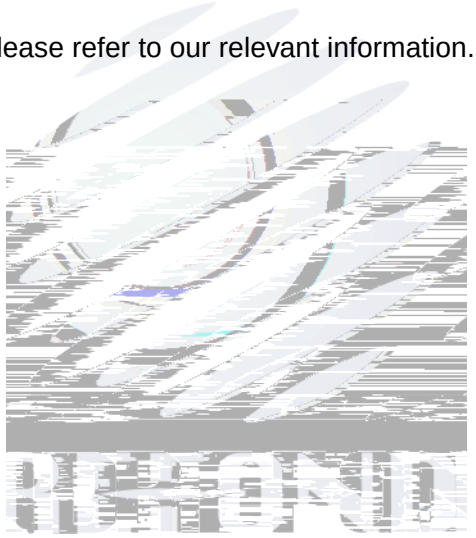
(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 65 5 for above 24 hours.

If the package is flatulence or damaged, please notify the sales staff to assist.

(9)Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) When using this product, you need to take good care to prevent it from causing harm to eyes and human body.

(11) Other points for attention, please refer to our relevant information.



Version History/

Date	Revisor	Version	Verifier	Remarks
2019-10-10		E0		
2020-09-10		E1		

www.refonduvled.com

Declare

This specification is written both in English and in Chinese and the latter is formal.